



COPPER ETCHANT POWDER

FORMULA:

Sulphuric Acid	:	50mL/L
Copper Etchant Powder	:	10g/L
D.I. Water	:	1 Litre

Add slowly with stirring (Gloves, Goggles!) of concentrated Sulphuric Acid. Then add with stirring Copper Etchant Powder till it dissolves. Allow to cool if warm and use.

Copper plated objects are dipped in the Copper Etchant solution until the colour of the deposit becomes uniformly chocolate coloured. Do not dip for a longer time.

This treatment improves the adhesion of plated copper on to the subsequently plated nickel.

Full details about bath preparation, analytical methods, effluent treatment method and trouble-shooting are available on request.

Warranty: The above information is based on our knowledge and experience and is given in good faith. RRR does not have control over the goods and over their usage, once they leave our premises. The normal precautions while handling chemicals must be followed (hand gloves, spectacles and so on), even when no hazard label is evident on the packing. The local regulations for treatment and discharge of chemicals must be followed. No liability arises out of handling or use.

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